



In re Patent Application of  
Tatsuya ARAO et al.  
Serial No. 09/826,416  
Filed: April 5, 2001  
For: SEMICONDUCTOR DEVICE AND)  
MANUFACTURING METHOD )  
THEREOF )

) Art Unit: 2811  
Examiner: T. Tran

**CERTIFICATE OF MAILING**

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**AMENDMENT**

Honorable Commissioner of Patents  
Washington, D.C. 20231

Sir:

In response to the Office Action dated April 10, 2002 please amend the above-  
identified application as follows:

**IN THE CLAIMS:**

Please cancel claims 1, 3, 5-11, and 25 and amend claims 23 and 28 as follows:

*B* 23. (Amended) A semiconductor device according to claim 2, wherein the third  
conductive film comprises at least one material selected from the group consisting of  
Ta, Ti, W and an alloy thereof.

*B* 28. (Amended) A semiconductor device according to claim 4, wherein the gate  
electrode comprises at least one material selected from the group consisting of Ta, Ti,  
W, and an alloy thereof.

Please add new claims 30-42 as follows:

-- 30. A semiconductor device comprising:

*B* 3  
*B* 2  
*B* 1  
*PC*  
*CS*

07/10/2002 SHINASSEI 00000088 09826416  
01 FC:103  
02 FC:102